

EMBEDDED PACKAGE STRUCTURE

ABSTRACT OF THE DISCLOSURE

An embedded package structure includes an insulation substrate, a first conductive layer, a second conductive layer, an electronic component and a passive component. The insulation substrate has a first conductive via and a second conductive via. The first conductive layer is formed on a top surface of the insulation substrate and contacted with the first conductive via. The second conductive layer is formed on a bottom surface of the insulation substrate, and contacted with the second conductive via. The electronic component is embedded within the insulation substrate. Moreover, plural conducting terminals of the electronic components are electrically connected with the first conductive layer and the second conductive layer through the first conductive via and the second conductive via. The passive component is located near a first side of the electronic component and separated from the electronic component. The passive component is at least partially embedded within the insulation substrate.

[Figure 1]